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JC07 Rec'd PCT/PTO 18 MAR 2002

Receipt
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ATTORNEY DOCKET NO.: 70031

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : MOMENI et al.
Serial No. : 09/763,785
Confirm. No. :
Filed : February 23, 2001
Mark/For : A METHOD....
Art Unit :
Examiner :
Dated : March 18, 2002

RECEIVED
APR 22 2002
TC 1700

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231
ATTENTION: Application Processing Division - Customer Correction Branch

REQUEST FOR CORRECTED FILING RECEIPT

Applicant respectfully requests that a corrected filing receipt be issued for the above identified application properly identifying the Foreign Application Country as **GERMANY**. The filing receipt received by Applicant's representatives lists the Foreign Application Country as EUROPE. This is incorrect.

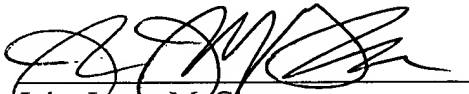
For verification, Applicant submits a copy of the Declaration evidencing that the Prior Foreign Application country is properly listed as GERMANY.

For your convenience, Applicant encloses a copy of the incorrect filing receipt with the correction indicated in red.

Based upon this evidence, Applicant respectfully requests that a corrected filing receipt be issued for the above identified application properly identifying the Foreign Application Country as **GERMANY**.

Favorable action is respectfully requested.

Respectfully submitted
for Applicant(s),

By: 
John James McGlew
Registration No. 31,903
For: McGLEW AND TUTTLE, P.C.

JJM:tf
70031.10

Enclosures: Copy of Incorrect Filing Receipt marked in red
copy of Declaration

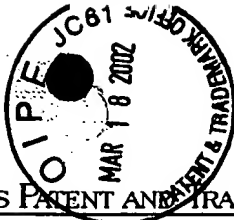
DATED: March 18, 2002
SCARBOROUGH STATION
SCARBOROUGH, NEW YORK 10510-0827
(914) 941-5600

NOTE: IF THERE IS ANY FEE DUE AT THIS TIME, PLEASE CHARGE IT TO OUR DEPOSIT ACCOUNT NO. 13-0410 AND ADVISE.

I HEREBY CERTIFY THAT THIS CORRESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS EXPRESS MAIL, REGISTRATION NO. EV071197703US IN AN ENVELOPE ADDRESSED TO: COMMISSIONER OF PATENTS AND TRADEMARKS, WASHINGTON, D.C. 20231, ON March 18, 2002.

McGLEW AND TUTTLE, P.C., SCARBOROUGH STATION,
SCARBOROUGH, NEW YORK 10510-0827

By:  Date: March 18, 2002



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/763,785	11/13/2001	1725	495	70031	6	19	3

CONFIRMATION NO. 3691

FILING RECEIPT



OC000000007506904

McGlew and Tuttle
Scarborough Station
Scarborough, NY 10510-0827

Date Mailed: 02/28/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Kaveh Momeni, Berlin, GERMANY;
Ghasem Azdasht, Berlin, GERMANY;

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/DE99/02554 08/18/1999

Foreign Applications

~~EUROPEAN PATENT OFFICE (EPO)~~ 198 38 532.3 08/25/1998
GERMANY

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Projected Publication Date: Not Applicable, filed prior to November 29, 2000.

Non-Publication Request: No

Early Publication Request: No

** SMALL ENTITY **

Title

Method and device for placing and remelting shaped pieces consisting of solder material

Preliminary Class

228

